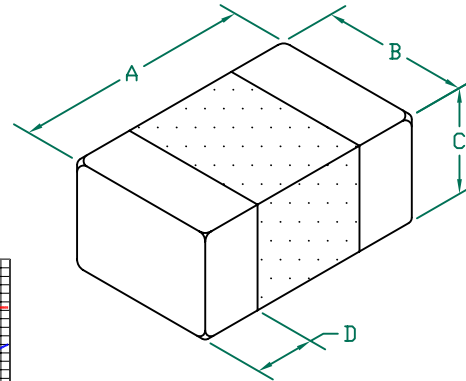


HI0805Q310R-10

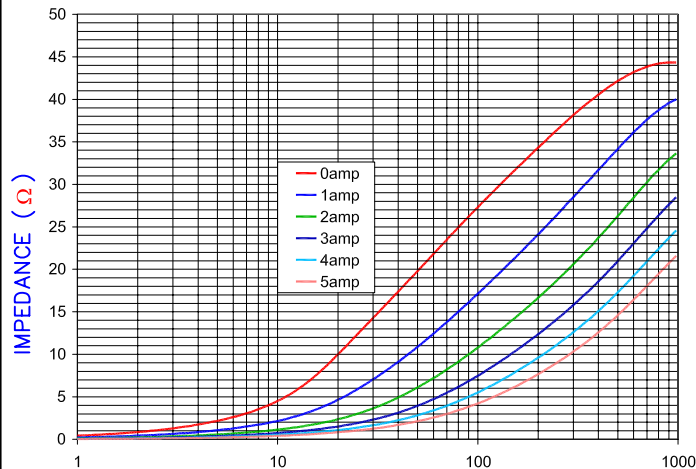
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]

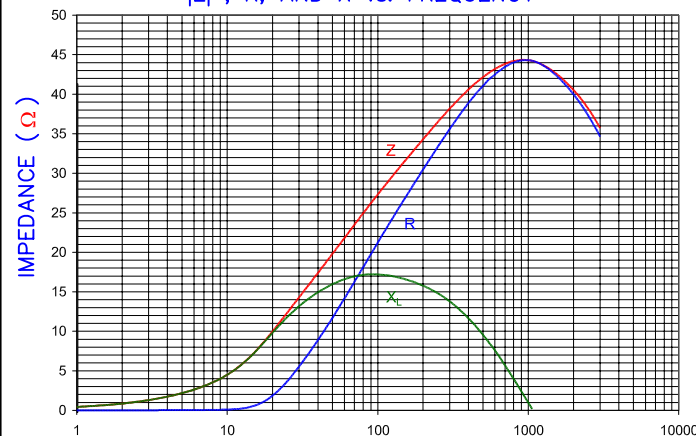


Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY



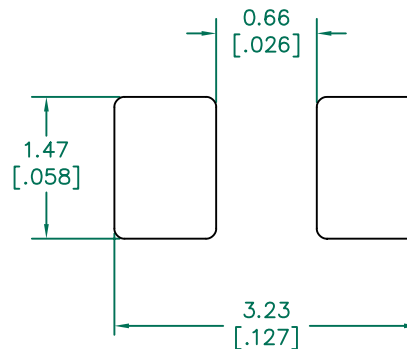
FREQUENCY (MHz)

Z R X_L

AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3124



LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)



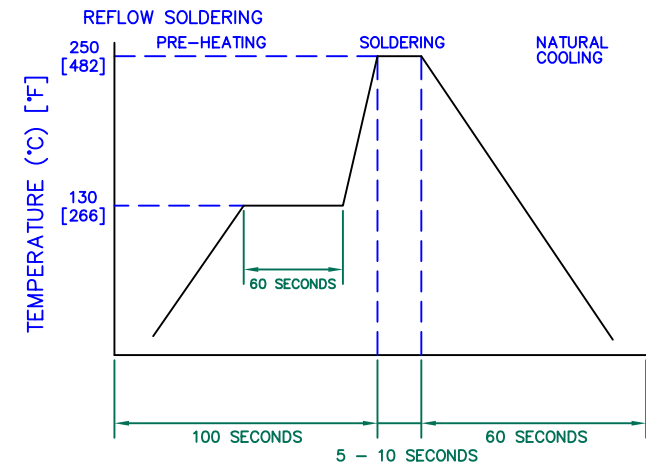
ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	31		
Minimum	23		
Maximum	39	0.025	4500 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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PROJECT/PART NUMBER:

HI0805Q310R-10

REV D PART TYPE: CO-FIRE DRAWN BY: TMB

DATE: 04/01/04

SCALE: NTS

SHEET: 2 of 2

CAD # HI0805Q310R-10-D

TOOL # -

REV	DESCRIPTION	DATE	INT
D	CHANGE TO PAPER TAPE	03/03/10	JUN
C	UPDATE COMPANY LOGO	06/05/09	JRK
B	UPDATE COMPANY LOGO ADD ROHS	01/16/08	JRK
A	ORIGINAL DRAFT	04/01/04	TMB